

Schottky Barrier Diode

Features

1. High reliability
2. Very low forward voltage
3. Small surface mounting type

Applications

Applications where a very low forward voltage is required

Absolute Maximum Ratings

$T_j=25^{\circ}\text{C}$

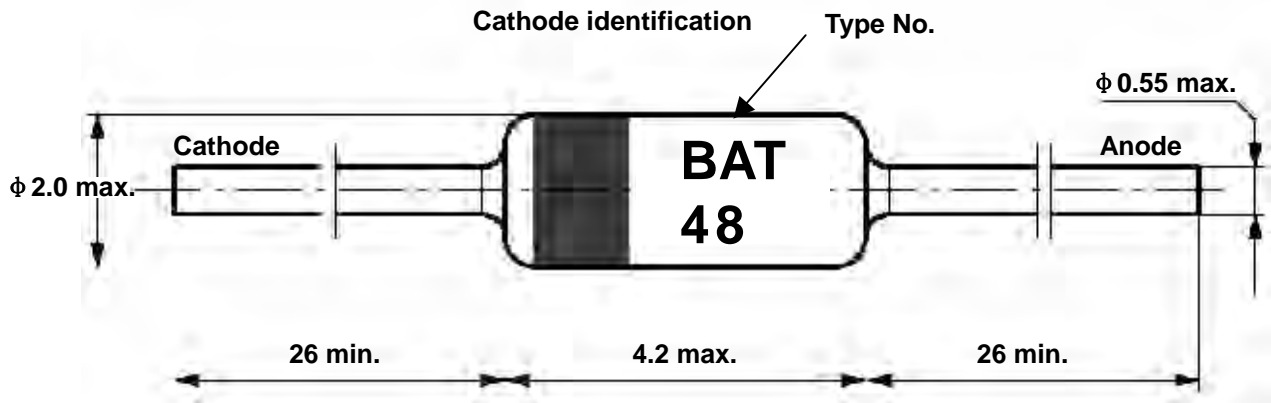
Parameter	Test Conditions	Symbol	Value	Unit
Repetitive peak reverse voltage		V_{RRM}	40	V
Forward continuous current	$T_{amb}=25^{\circ}\text{C}$	I_F	350	mA
Repetitive peak forward current	$T_{amb}=25^{\circ}\text{C}$, $t_p \leq 1\text{ s}$	I_{FRM}	1	A
Surge forward current	$t_p \leq 10\text{ms}$, $T_{amb}=25^{\circ}\text{C}$	I_{FSM}	7.5	A
Power dissipation	$T_{amb}=65^{\circ}\text{C}$	P_{tot}	330	mW
Maximum junction temperature		T_j	125	$^{\circ}\text{C}$
Ambient operating temperature range		T_A	-65~+125	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-65~+150	$^{\circ}\text{C}$

Maximum Thermal Resistance

$T_j=25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mm×50mm×1.6mm	R_{thJA}	300	$^{\circ}\text{C}/\text{W}$

Dimensions in mm



Standard Glass Case
JEDEC DO 35

Characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise specified)

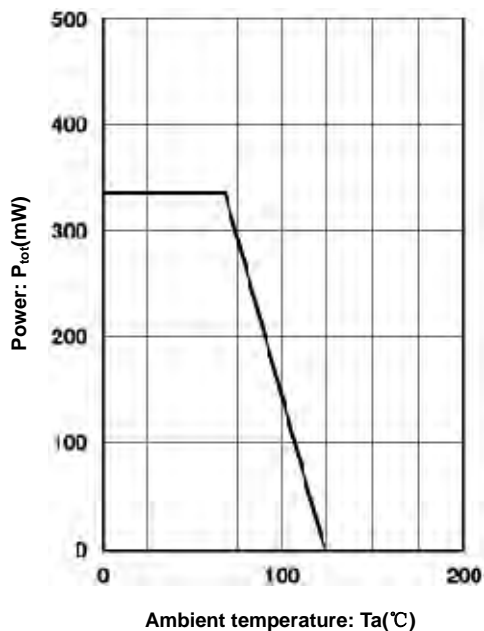


Figure 1. Admissible power dissipation vs. ambient temperature

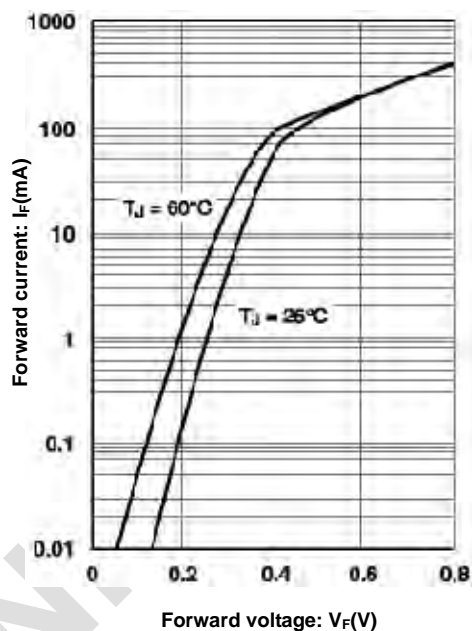


Figure 2. Forward characteristics

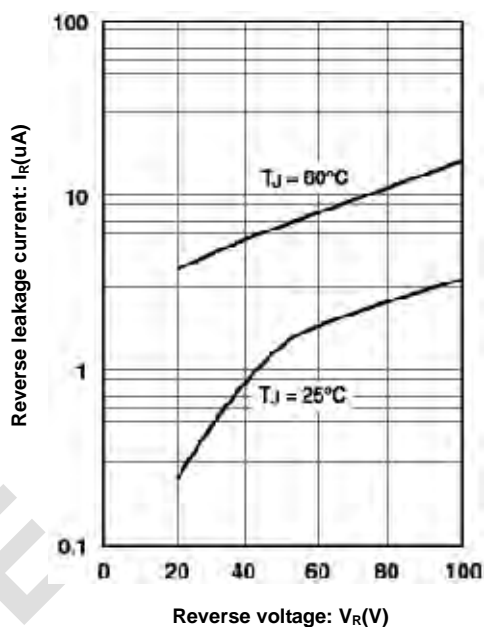


Figure 3. Typical reverse characteristics

Electrical Characteristics

T_j=25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse breakdown voltage	V _{(BR)R}	I _R =10 μA (pulsed)	40	-	-	V
Leakage Current Pulse test tp<300 μs, δ<2%	I _R	V _R =10V	-	-	2	μA
		V _R =10V, T _j =60°C	-	-	15	μA
		V _R =20V	-	-	5	μA
		V _R =20V, T _j =60°C	-	-	25	μA
		V _R =40V	-	-	25	μA
		V _R =40V, T _j =60°C	-	-	50	μA
Forward voltage Pulse test tp<300 μs, δ<2%	V _F	I _F =0.1mA	-	-	0.25	V
		I _F =1mA	-	-	0.30	V
		I _F =10mA	-	-	0.40	V
		I _F =50mA	-	-	0.50	V
		I _F =200mA	-	-	0.75	V
		I _F =500mA	-	-	0.90	V
Capacitance	C _{tot}	V _R =1V, f=1MHz	-	12	-	pF